

DERWENT-ACC-NO: 1984-303625

DERWENT-WEEK: 198449

COPYRIGHT 1999 DERWENT INFORMATION LTD

TITLE: Printed circuit board mfr. - forming etching resist by  
offset printing providing reliable resist and high  
productivity NoAbstract NoDwg

PATENT-ASSIGNEE: MATSUSHITA ELEC IND CO LTD[MATU]

PRIORITY-DATA: 1983JP-0063277 (April 11, 1983)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 59188991 A	October 26, 1984	N/A	004	N/A

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 59188991A	N/A	1983JP-0063277	April 11, 1983

INT-CL (IPC): H05K003/06

ABSTRACTED-PUB-NO:

EQUIVALENT-ABSTRACTS:

TITLE-TERMS: PRINT CIRCUIT BOARD MANUFACTURE FORMING ETCH  
RESIST OFFSET PRINT  
RELIABILITY RESIST HIGH PRODUCE NOABSTRACT

DERWENT-CLASS: G05 L03 V04

CPI-CODES: G02-A05B; G06-D06; L03-H04E3;

DERWENT-ACC-NO: 1984-252691

DERWENT-WEEK: 198441

COPYRIGHT 1999 DERWENT INFORMATION LTD

TITLE: Printed circuit board - produced by forming etching  
resist film on copper foil of copper clad laminate using  
offset printing technique NoAbstract NoDwg

PATENT-ASSIGNEE: MATSUSHITA ELEC IND CO LTD[MATU]

PRIORITY-DATA: 1983JP-0023863 (February 17, 1983)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 59151488 A	August 29, 1984	N/A	004	N/A

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 59151488A	N/A	1983JP-0023863	February 17, 1983

INT-CL (IPC): H05K003/06

ABSTRACTED-PUB-NO:

EQUIVALENT-ABSTRACTS:

TITLE-TERMS: PRINT CIRCUIT BOARD PRODUCE FORMING ETCH RESIST  
FILM COPPER FOIL  
COPPER CLAD LAMINATE OFFSET PRINT TECHNIQUE NOABSTRACT

ADDL-INDEXING-TERMS:  
PCB

DERWENT-CLASS: L03 V04

CPI-CODES: L03-H04E2;